IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

ZHONGNING LIANG ET AL

NL 000195

Serial No.

Filed: CONCURRENTLY

SEMICONDUCTOR DEVICE

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to calculation of the filing fee and examination, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as follows:

3. (Amended) A semiconductor device as claimed in claim 1, wherein a stack of layered structures is present.

7. (Amended) A semiconductor device as claimed in claim 1, wherein the via lines are patterned in the form of a grid.

8. (Amended) A method of mahufacturing a semiconductor device as claimed in claim 1, comprising the steps of:

- forming a meta/ layer; (a)
- forming a dielectric layer; (b)